



GENERAL DESCRIPTION

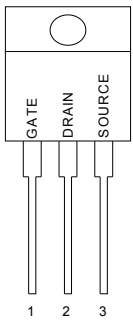
This advanced high voltage MOSFET is designed to withstand high energy in the avalanche mode and switch efficiently. This new high energy device also offers a drain-to-source diode with fast recovery time. Designed for high voltage, high speed switching applications such as power supplies, converters, power motor controls and bridge circuits.

FEATURES

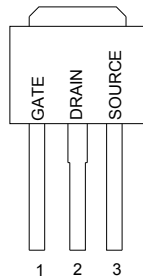
- ◆ SJ MOS
- ◆ Higher Current Rating
- ◆ Lower $R_{ds(on)}$
- ◆ Lower Capacitances
- ◆ Lower Total Gate Charge

PIN CONFIGURATION

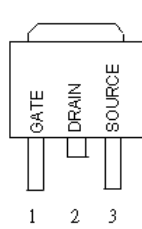
TO-220/TO-220FP
Top View



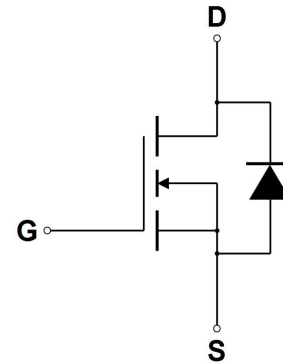
TO-251
Front View



TO-252
Front View



SYMBOL



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain to Current – Continuous	$I_{D(1)}$	15.1	A
– Pulsed	I_{DM}	45.3	
Gate-to-Source Voltage – Continue	V_{GS}	± 20	V
Total Power Dissipation TO-251/TO-252	P_D	105.9	W
TO-220		174	
TO-220FP		37	
Derate above 25°C TO-251/TO-252	P_D	0.85	W/°C
TO-220		1.39	
TO-220FP		0.29	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C
Single Pulse Drain-to-Source Avalanche Energy – $T_J = 25^\circ\text{C}$ ($V_{DD} = 100\text{V}, V_{GS} = 10\text{V}, I_L = 4\text{A}, L = 10\text{mH}, R_G = 25\Omega$)	E_{AS}	80	mJ
Thermal Resistance – Junction to Case TO-251/TO-252	θ_{JC}	1.18	°C/W
TO-220		0.72	
TO-220FP		3.4	
– Junction to Ambient TO-251/TO-252/ TO-220/ TO-220FP	θ_{JA}	62.5	
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	T_L	260	°C

(1) Drain current limited by maximum junction temperature (TO220)



GWM16S60

POWER FIELD EFFECT TRANSISTOR

ORDERING INFORMATION

Part Number	TOP MARK	Part Number	Packing Mthod	Note
GWM16S60XN251 (Note1)	GWM16S60X	TO-251	Tube	
GWM16S60XN252 (Note1)	GWM16S60X	TO-252	Tube	
GWM16S60XN252TR(Note1)	GWM16S60X	TO-252	Tape and Reel	
GWM16S60XN220 (Note1)	GWM16S60X	TO-220	Tube	
GWM16S60XN220FP (Note1)	GWM16S60X	TO 220FP	Tube	

Note1: X : Suffix for Halogen Free and PB Free Product

ELECTRICAL CHARACTERISTICS

Unless otherwise specified, $T_J = 25^\circ\text{C}$.

Characteristic		Symbol	GWM16S60			Units
			Min	Typ	Max	
Drain-Source Breakdown Voltage ($V_{GS} = 0V, I_D = 250 \mu A$)		$V_{(BR)DSS}$	600			V
Drain-Source Leakage Current ($V_{DS} = 600V, V_{GS} = 0V$)		I_{DSS}			1	μA
Gate-Source Leakage Current-Forward ($V_{gsf} = 20V, V_{DS} = 0V$)		I_{GSSF}			100	nA
Gate-Source Leakage Current-Reverse ($V_{gsr} = -20V, V_{DS} = 0V$)		I_{GSSR}			100	nA
Gate Threshold Voltage ($V_{DS} = V_{GS}, I_D = 250 \mu A$)		$V_{GS(th)}$	2	3	4	V
Static Drain-Source On-Resistance ($V_{GS} = 10V, I_D = 5.4A$) *		$R_{DS(on)}$		0.25	0.305	Ω
Input Capacitance	$(V_{DS} = 100V, V_{GS} = 0V,$ $f = 1.0 \text{ MHz})$	C_{iss}		1063		pF
Output Capacitance		C_{oss}		45		pF
Reverse Transfer Capacitance		C_{rss}		51		pF
Turn-On Delay Time	$(V_{DD} = 250V, I_D = 16A,$ $V_{GS} = 10V,$ $R_G = 9.1\Omega)$ *	$t_{d(on)}$		12.2		ns
Rise Time		t_r		35.8		ns
Turn-Off Delay Time		$t_{d(off)}$		39.6		ns
Fall Time		t_f		27.4		ns
Total Gate Charge	$(V_{DS} = 400V, I_D = 16A,$ $V_{GS} = 10V)$ *	Q_g		30.8		nC
Gate-Source Charge		Q_{gs}		6.9		nC
Gate-Drain Charge		Q_{gd}		14.4		nC
SOURCE-DRAIN DIODE CHARACTERISTICS						
Forward On-Voltage(1)	$(I_S = 16A,$ $d_i/d_t = 100A/\mu s)$	V_{SD}			1.5	V
Forward Turn-On Time		t_{on}		**		ns
Reverse Recovery Time		t_{rr}		536		ns

* Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

** Negligible, Dominated by circuit inductance



TYPICAL ELECTRICAL CHARACTERISTICS

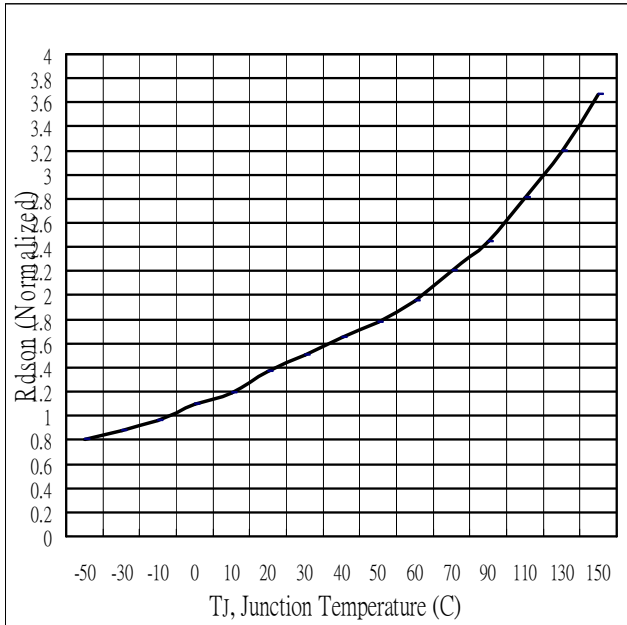


Fig 1. On-Resistance Variation with vs. Temperature

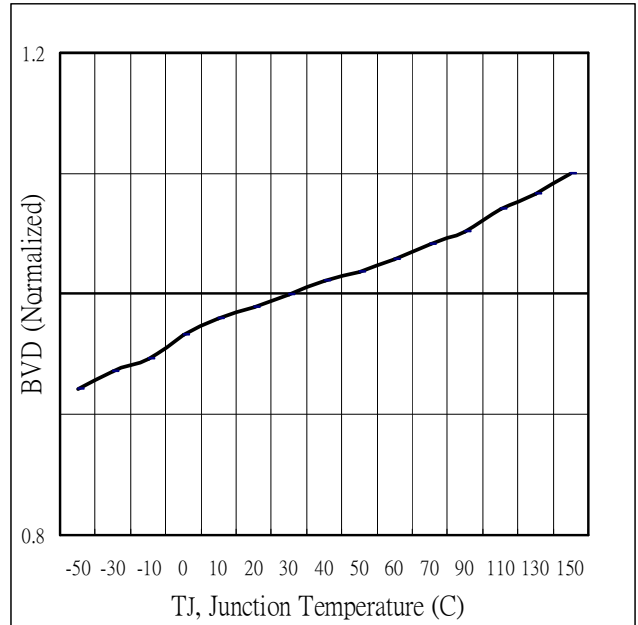


Fig.2 Breakdown Voltage Variation vs. Temperature

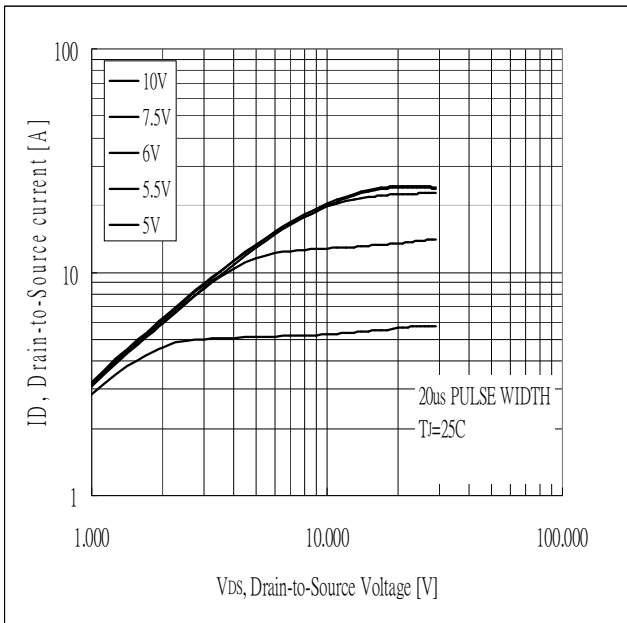


Fig 3. Typical Output Characteristics

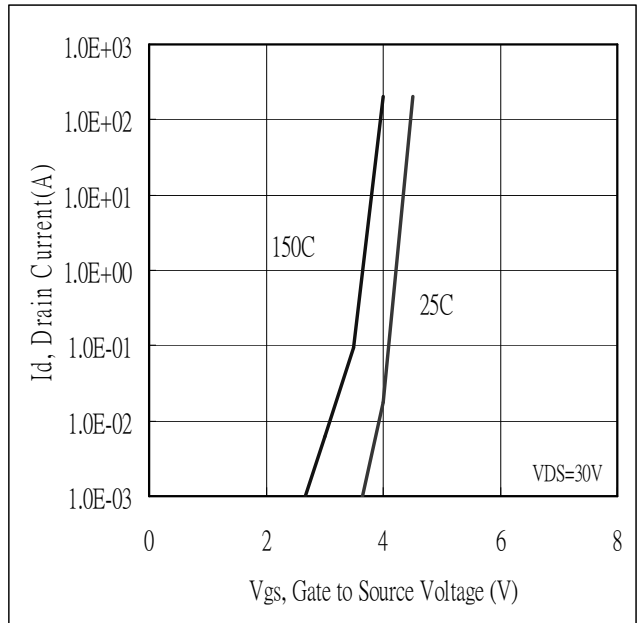


Fig 4. Typical Transfer Characteristics

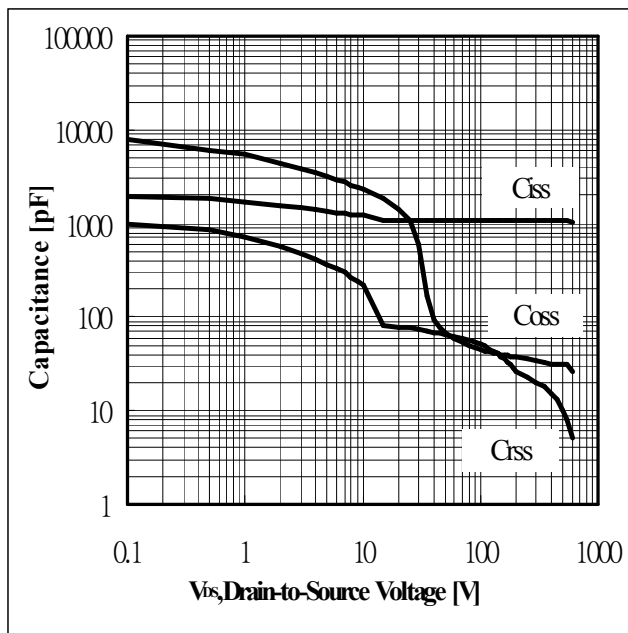


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

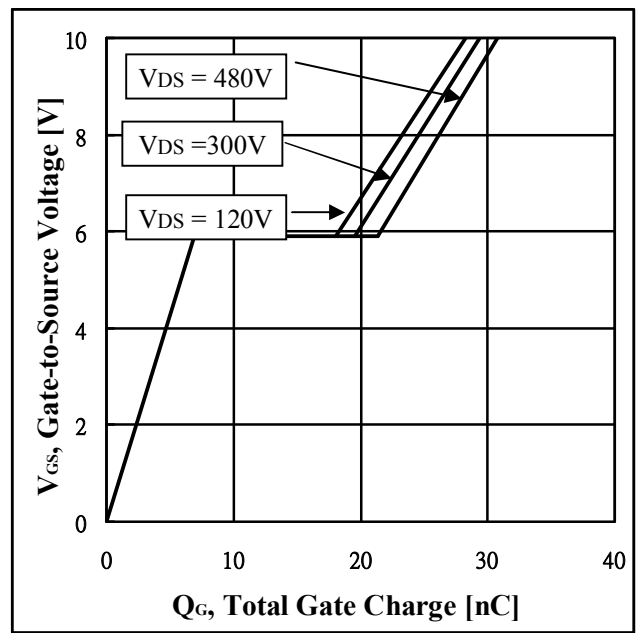


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage